

The eGaN<sup>®</sup> FET  
Journey Continues



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Comparison of 6.78 MHz Amplifier Topologies for  
33W, Highly Resonant Wireless Power Transfer

*Efficient Power Conversion Corporation*

- Wireless power trends
- AirFuel™ Class 4
- High power capable amplifiers
- Experimental results
- Summary

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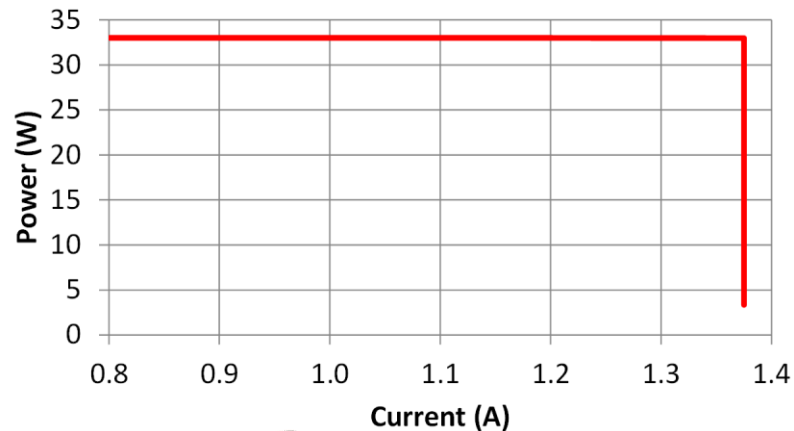
## Higher power

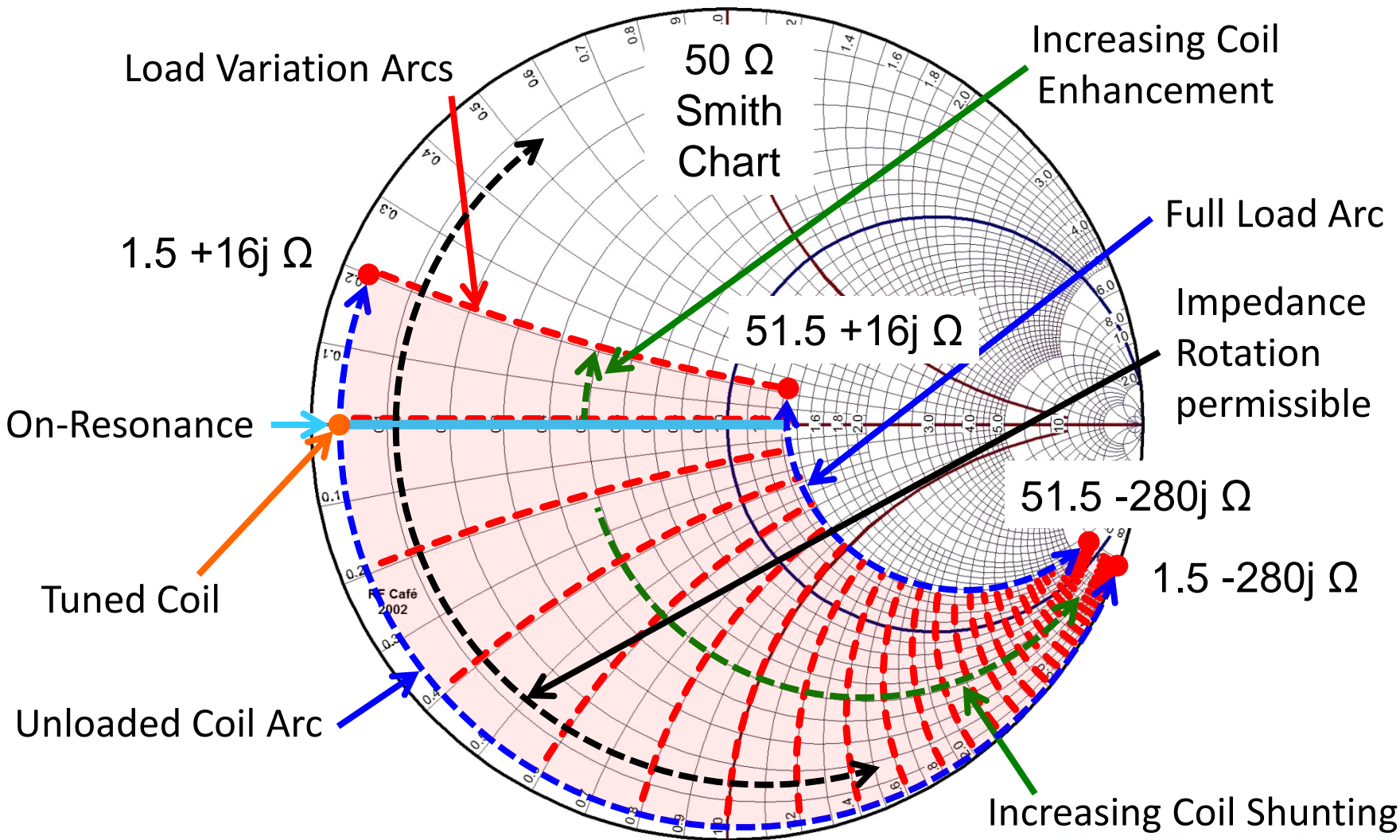
- More devices needing wireless power
  - Smartphones (~6 W)
  - Tablets (~13 W)
  - Small laptops (~25 W)
- Fast charging
- Move toward wireless power, not just charging

- 1.375 A<sub>RMS</sub> into the coil or de-rated at 33 W
- 6.78 MHz



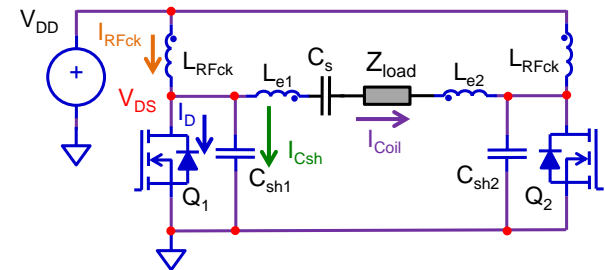
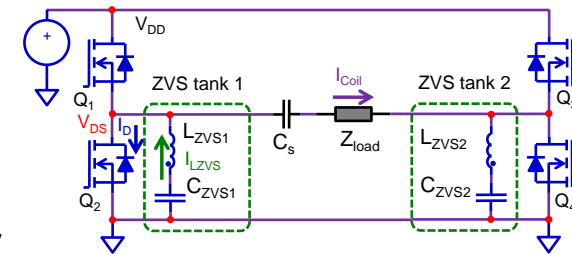
- Devices
  - 1x Category 5 (20 W)up to
  - 3x Category 3 (6.5 W)



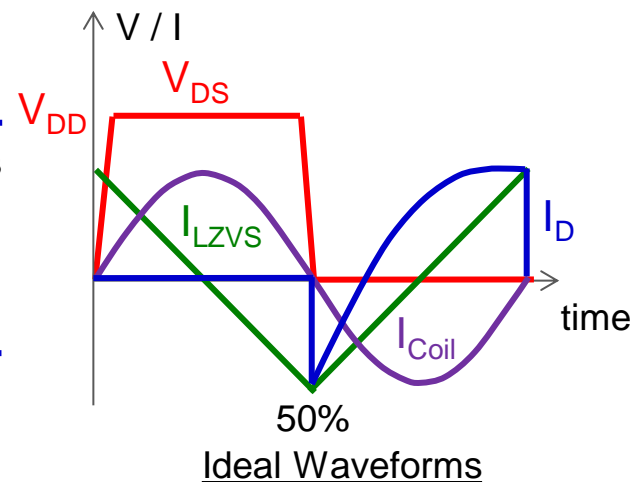
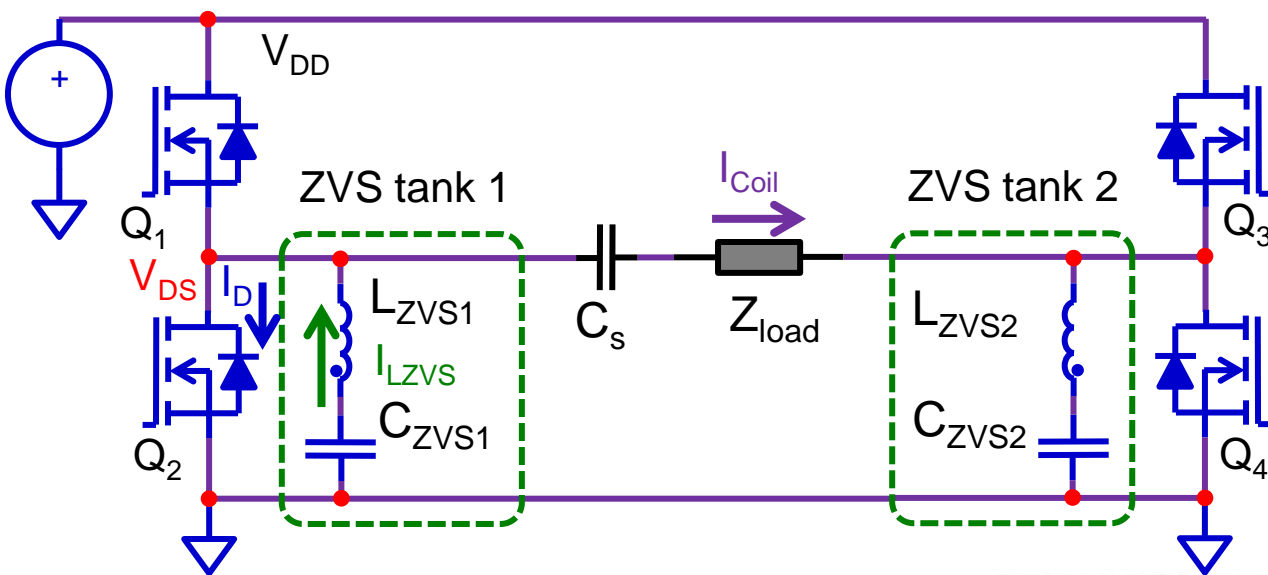
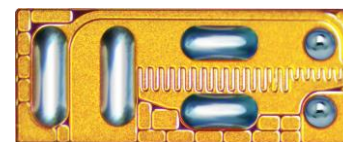




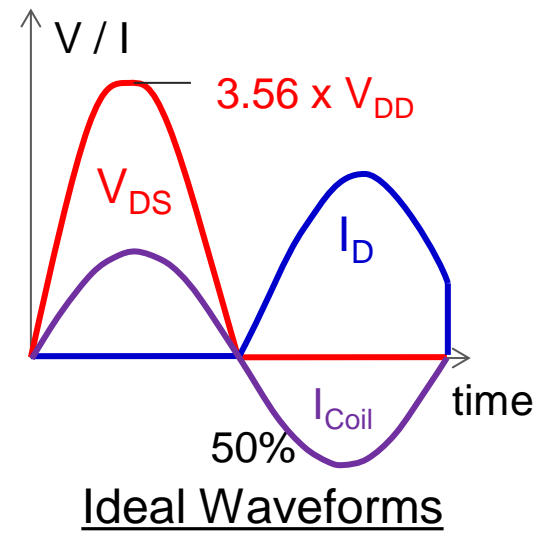
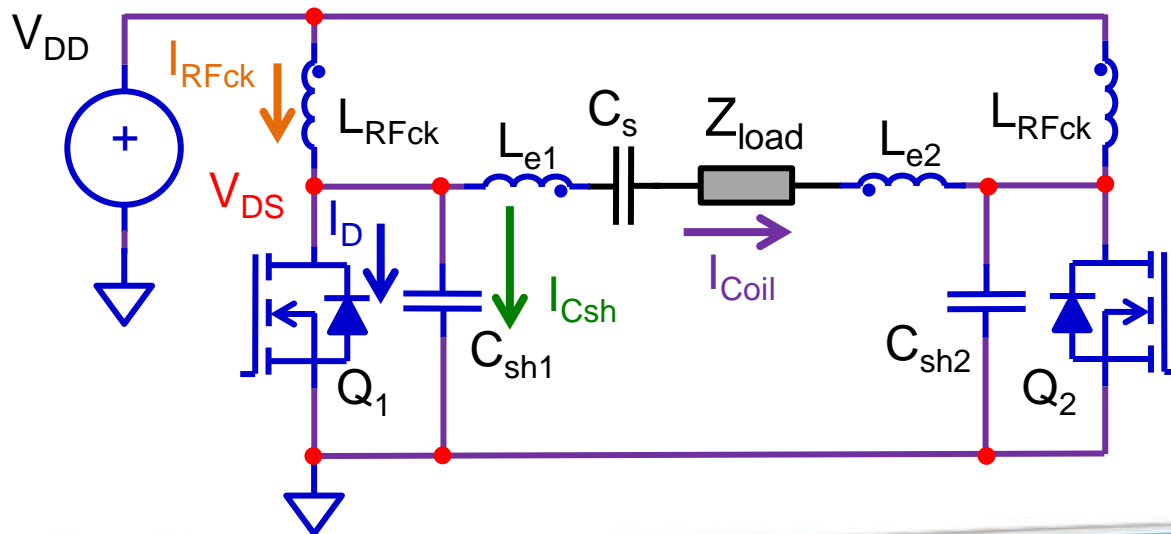
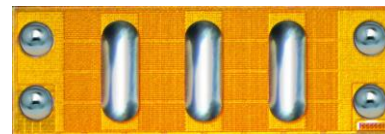
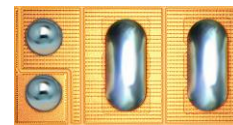
- Differential mode ZVS class D
  - Robust to load variations
  - Requires level shifting gate driver
  
- Differential mode class E
  - Simple and low cost
  - Susceptible to load variations



- Analytical design:  $-50j \Omega$  through  $+50j \Omega$  &  $1 \Omega$  through  $52 \Omega$
- Optimal  $L_{ZVS}$  and dead-time:
  - EPC2007C (30 m $\Omega$ ) = 390 nH, 8ns
  - EPC8010 (160 m $\Omega$ ) = 500 nH, 3.5 ns
- Requires synchronous bootstrap

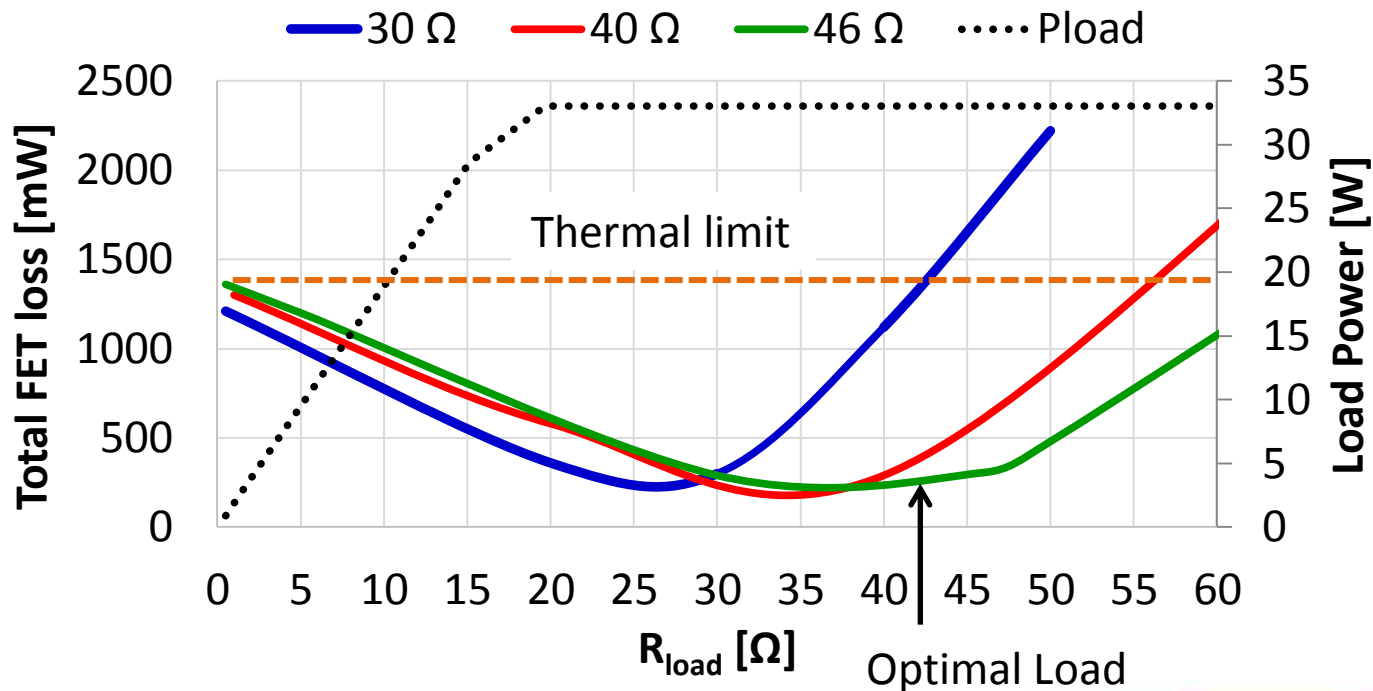


- Optimal load point analysis by simulation
- Realizable design FET selection:
  - EPC2012C (100 mΩ),  $C_{sh} = 68$  pF
  - EPC2019 (50 mΩ),  $C_{sh} = 0$  pF
- $L_e = 600$  nH,  $L_{RFck} = 39$  μH





- LTSpice simulation: Total FET power loss
- Optimal load resistance – lowest cumulative FET loss over entire Load resistance range

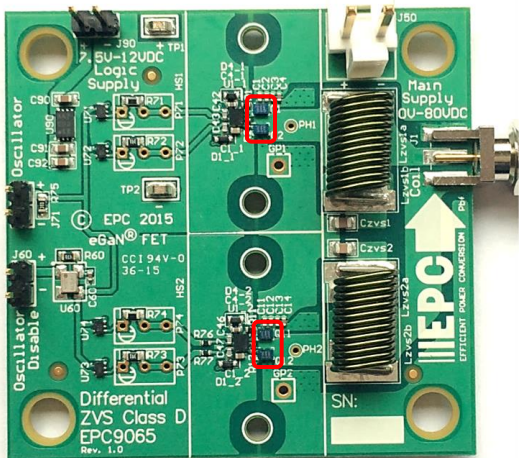


# Experimental Units

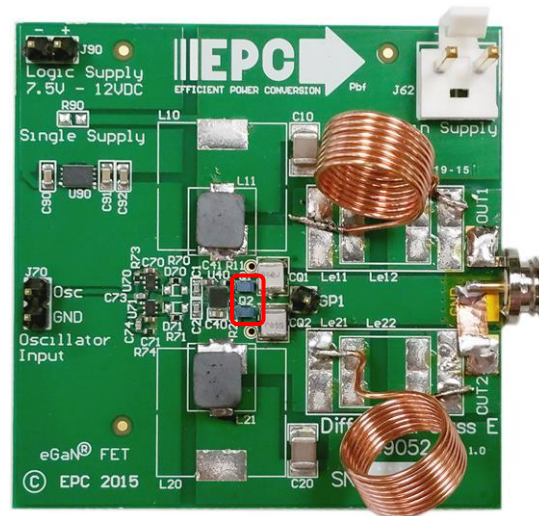
## ZVS class D

## Class E

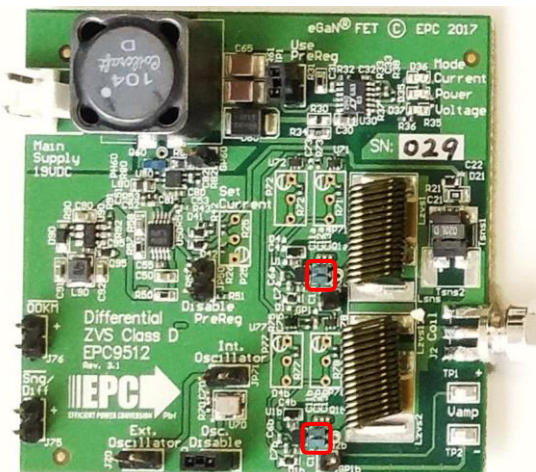
EPC2007C



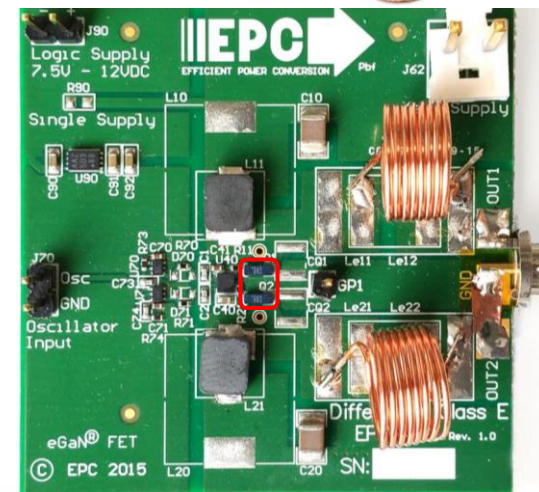
EPC2012C



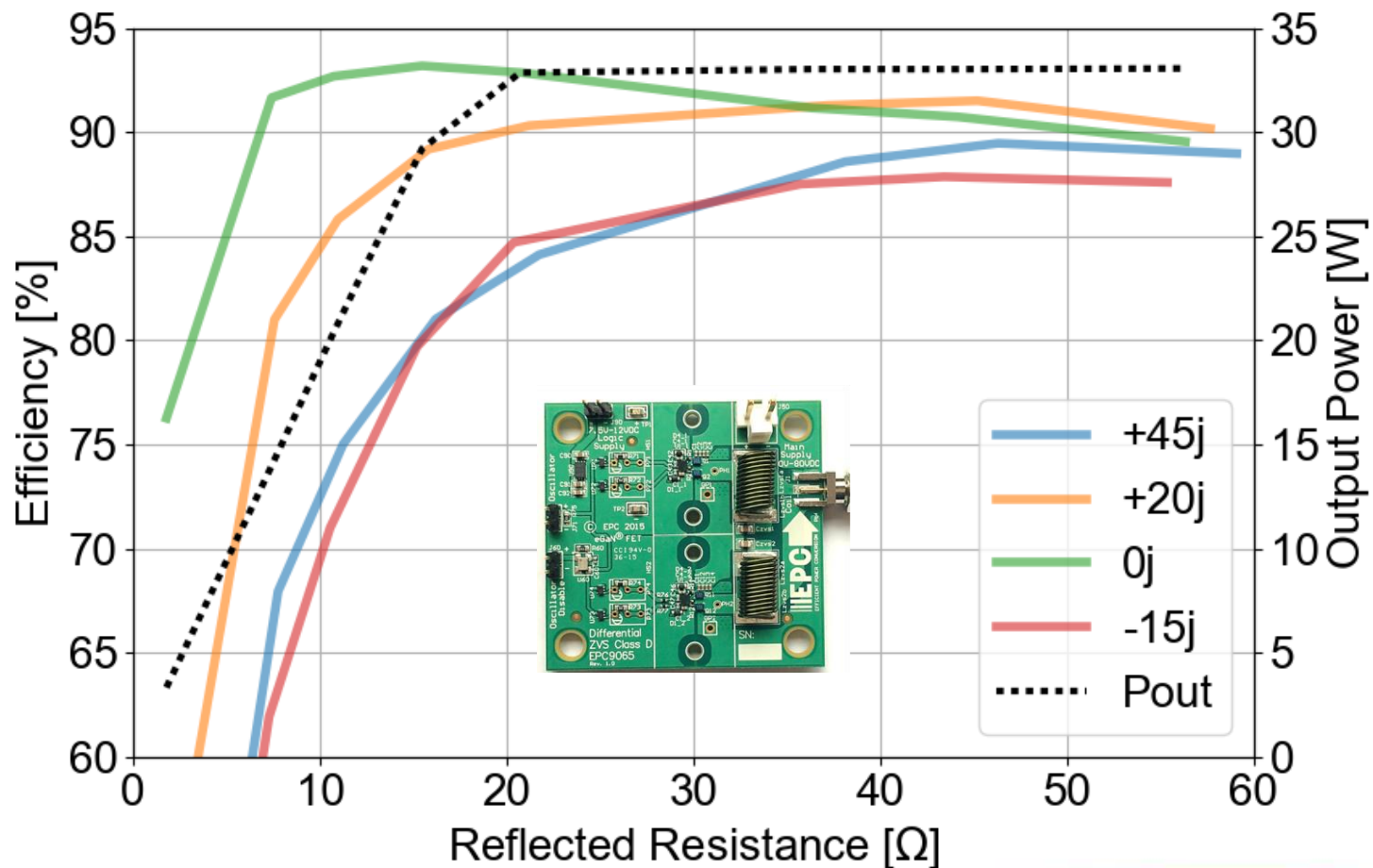
EPC8010



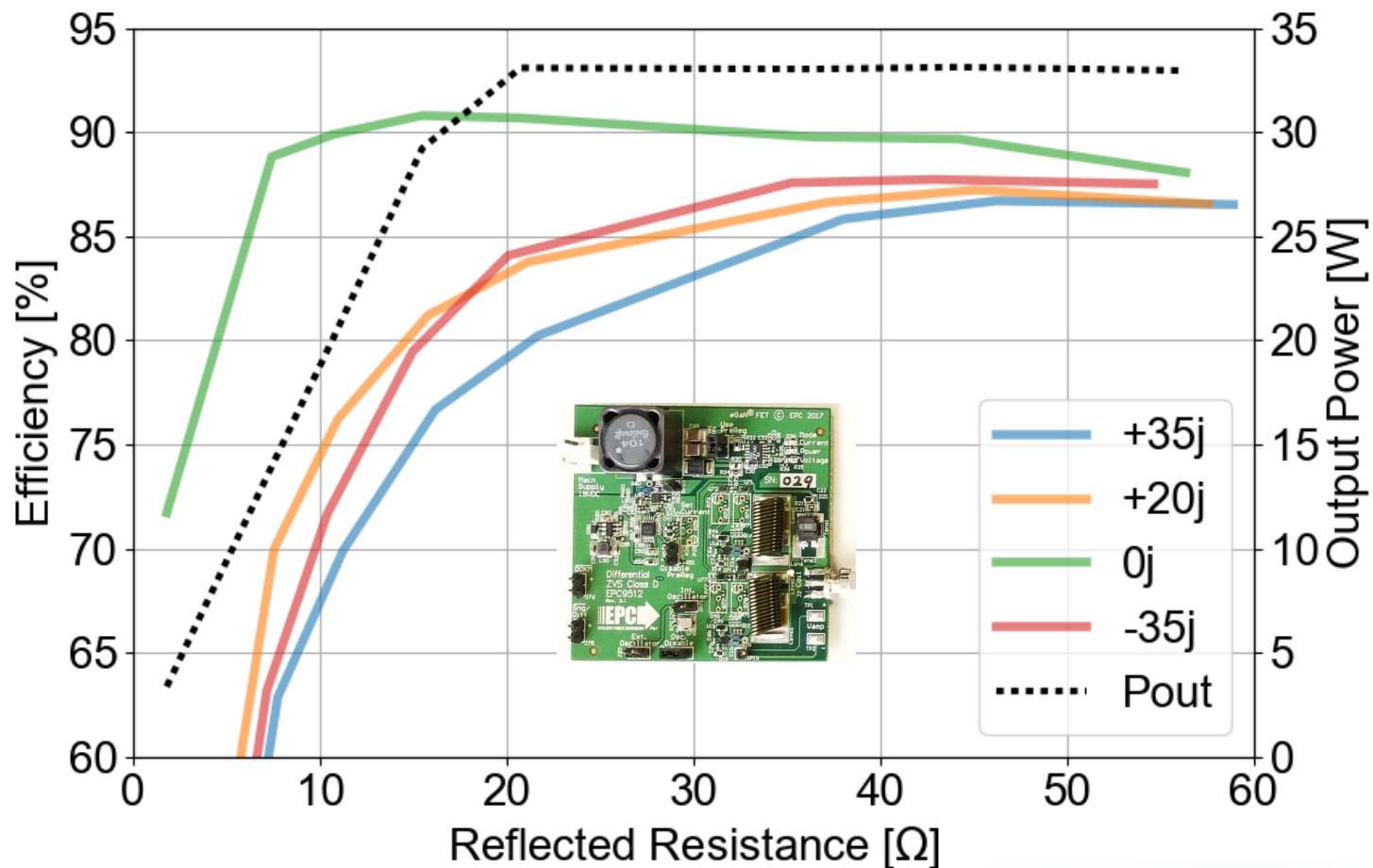
EPC2019



- Thermally limited at extreme load impedances
- **60j  $\Omega$**  range class 4 capable

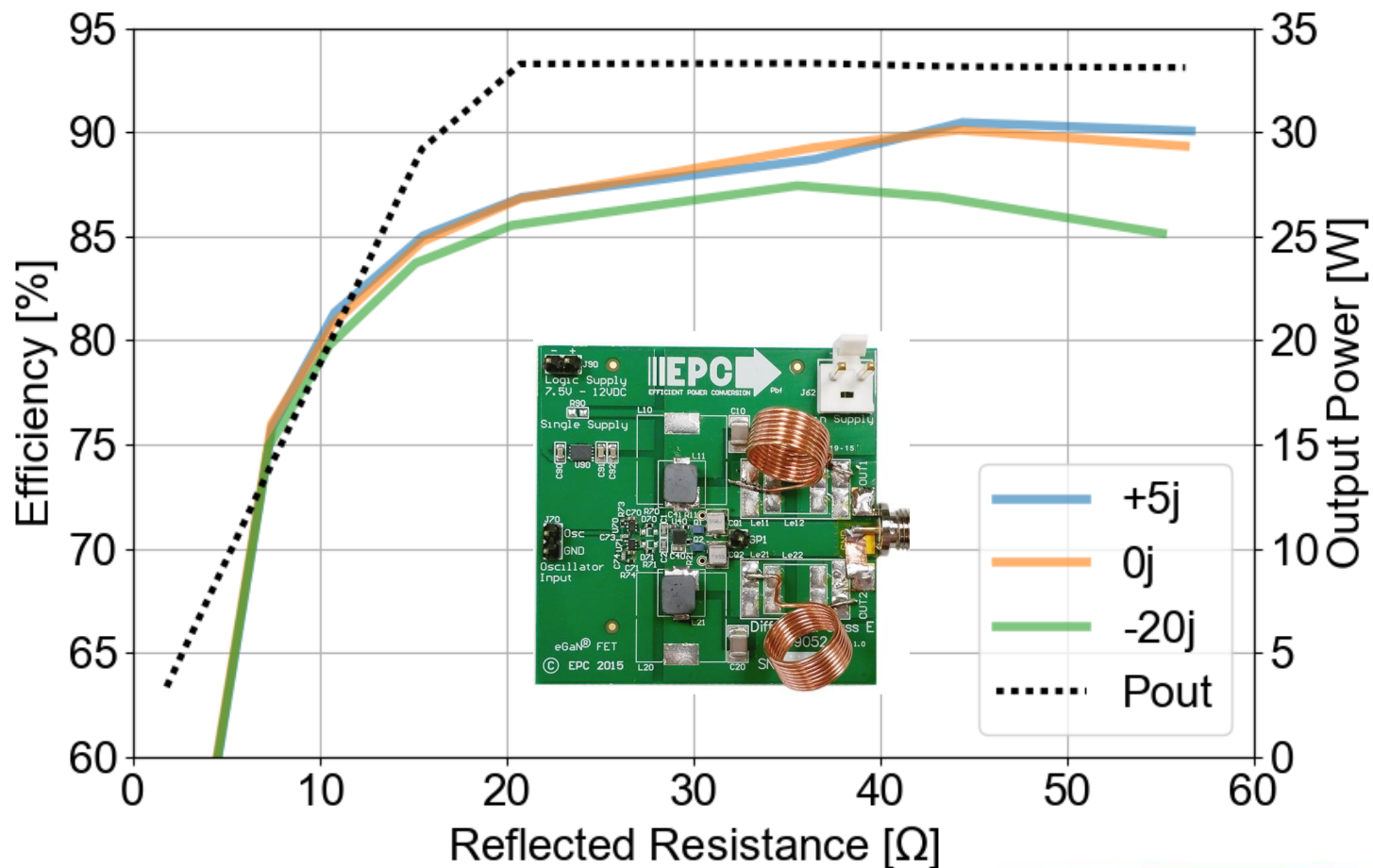


- Thermally limited at extreme load impedances
- **70j  $\Omega$**  range class 4 capable



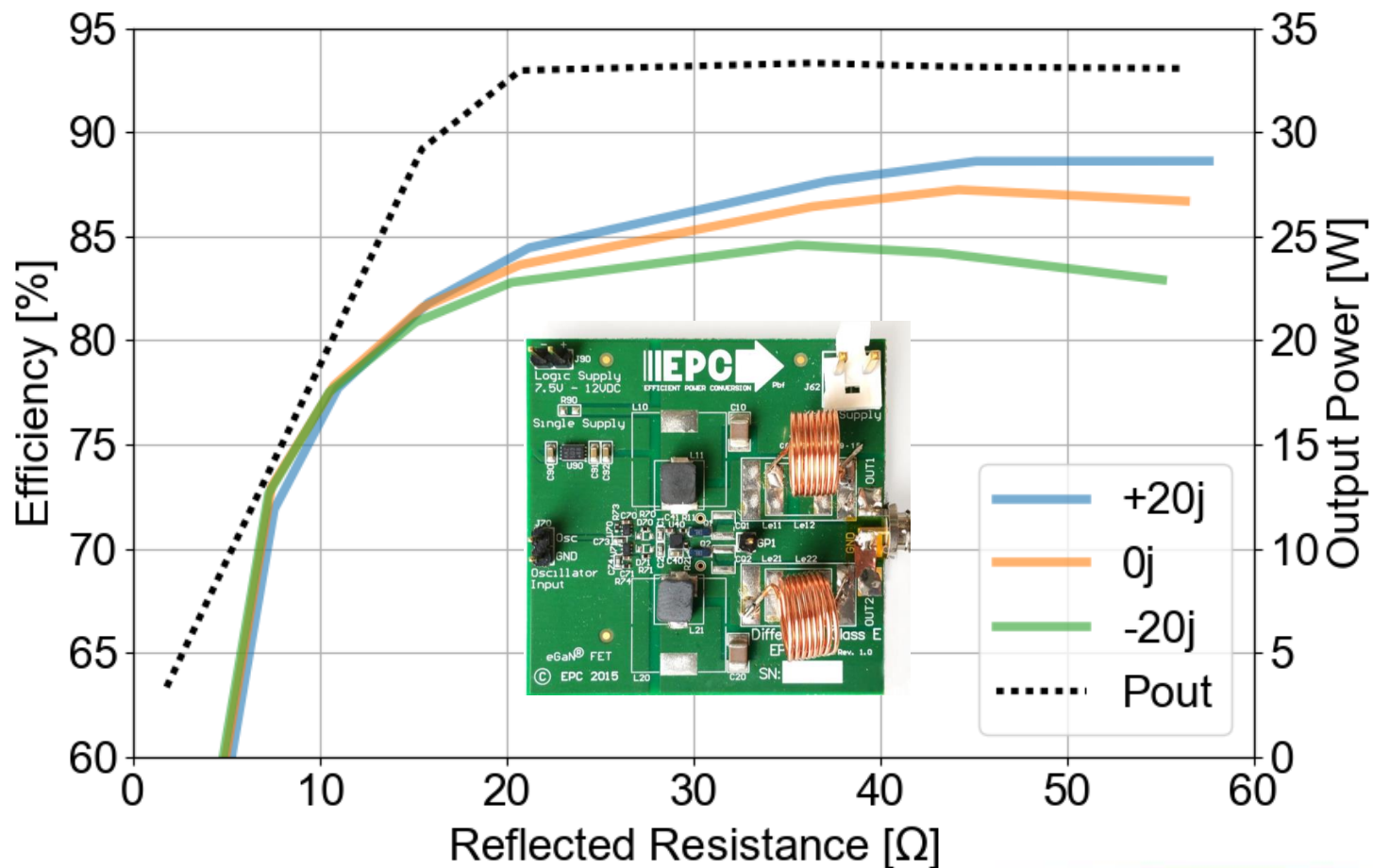


- Thermally and voltage limited
- **25j  $\Omega$**  range class 4 capable

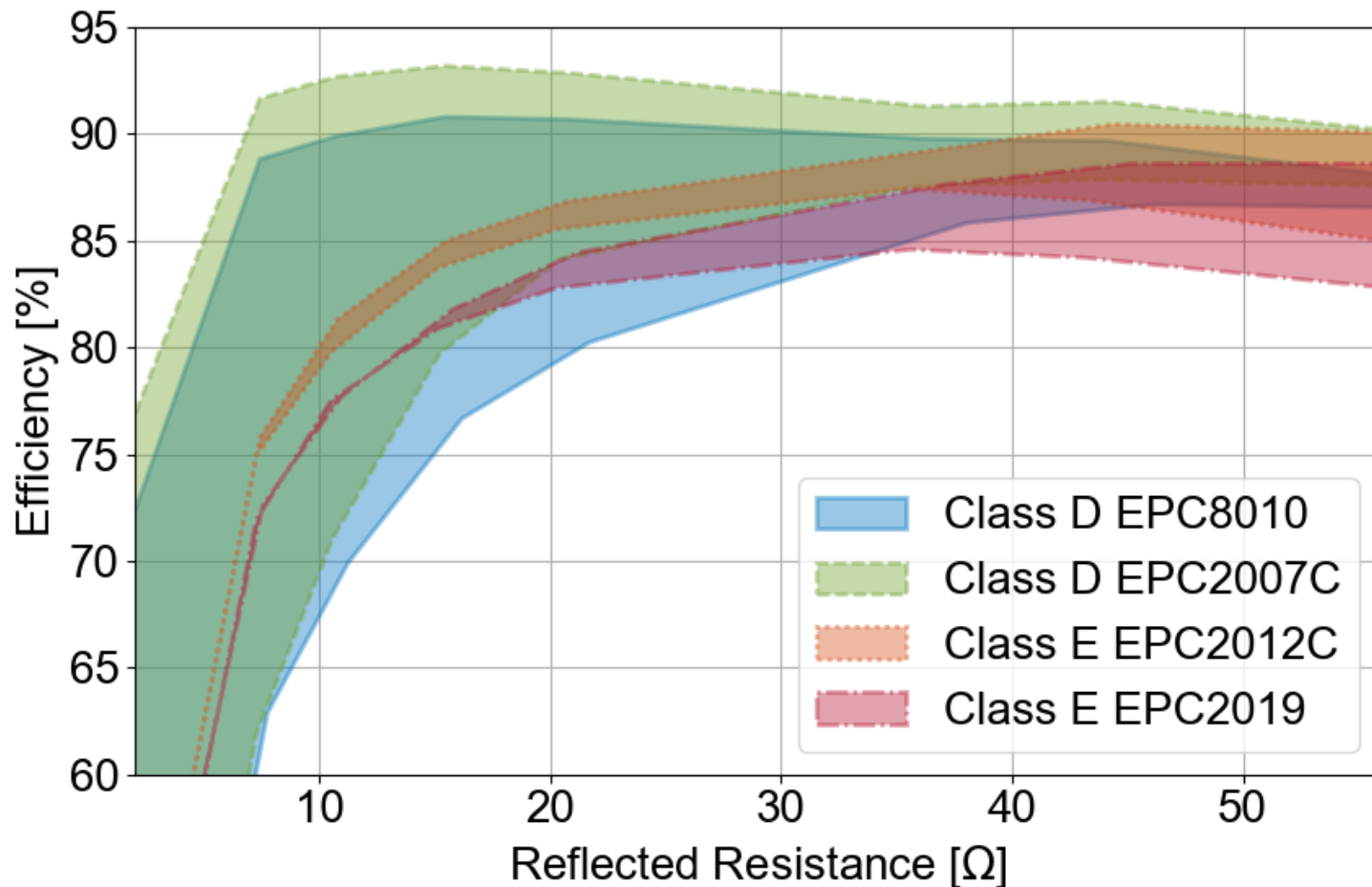




- Thermally and voltage limited
- **40j  $\Omega$**  range class 4 capable



Class D - wide variation due to wider impedance range



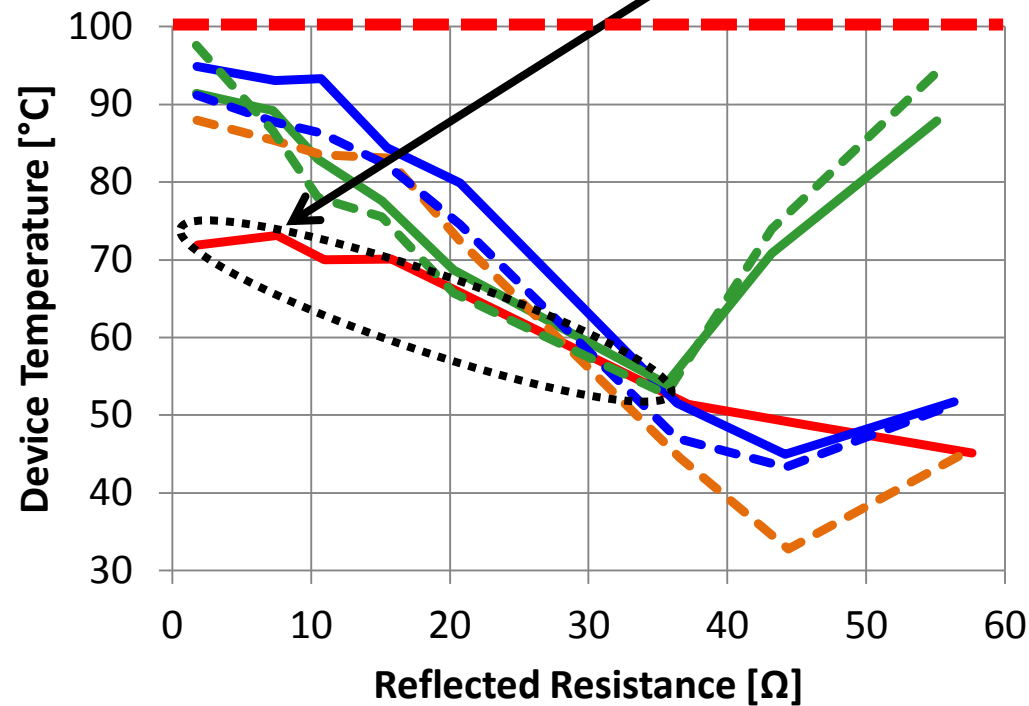
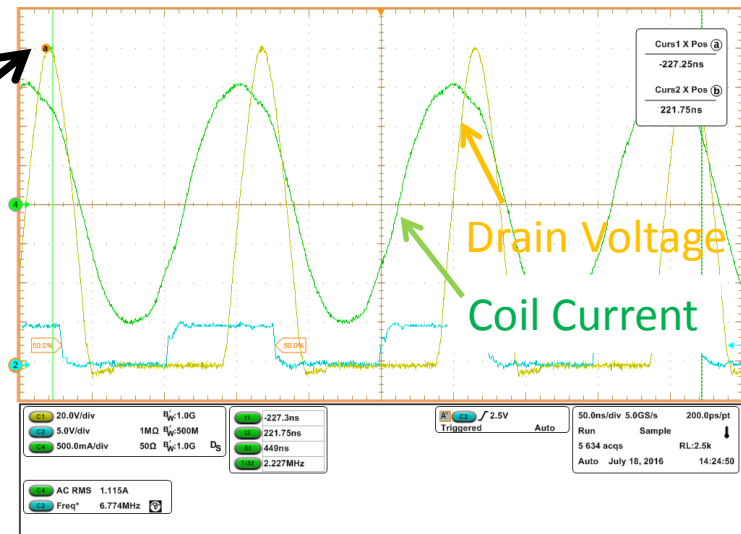
- Class E performance nearly identical when compared over same impedance range
- Class D yields greater improvement from lower  $R_{DSon}$

Topology	eGaN FET ( $R_{DSon}$ )	Efficiency Range at max. Power	Reactance Range	Relative Range
ZVS class-D	EPC8010	80.2% to 90.6%	-35j to +35j $\Omega$	70j $\Omega$
	EPC2007C	<b>87.5% to 92.8%</b>	-15j to +45j $\Omega$	60j $\Omega$
Class-E	EPC2012C	85.1% to 90.4%	<b>-20j to +5j <math>\Omega</math></b>	25j $\Omega$
	EPC2019	82.8% to 88.6%	-20j to +20j $\Omega$	40j $\Omega$

# Class E – Limitations

- 160 V limit – 80% of rated
- or
- 100°C

Voltage limited



- +20j
  - 0j
  - -20j
  - +5j Ω
  - 0j
  - -20j
- EPC2019
- EPC2012C

- 33 W wireless power amplifiers compared
  - Wider impedance range leads to lower cost systems
  - ZVS Class D: 75% wider impedance range than class E
  - Class E: Easier to drive and more popular
- eGaN FETs yield high efficiency at full power
  - Lower  $R_{DS(on)}$  improves performance  
*but higher  $C_{OSS}$  leads to*
  - Higher soft-switching energy for class D
  - Design with negative  $C_{sh}$  for Class E





*The end of the  
road for silicon...  
but a clear road  
ahead for GaN  
FETs and ICs!*